IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	© Copyright 2005. IPO	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfc Information			
upplier Infori	mation								,					
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi											2024-04-25			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stew	vards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Repres	sentative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
Product-Env-Stew	vards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number Mfr Ite		em Number Mfr Item Name			Effective		Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type
		NCP508MT15TBG 50		50 MA LDO			2024-04-25		M	MY1		05	mg	Each
Ianufacturing	g Proccess Informati	on												·
Terminal Plating / Grid Array Material Ter			Perminal Base Alloy J-STD-020 MSL Ratio			Rating	Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles			
SnAgCu		C	CU Alloy 1			260 C 30		30	second	s 3				
omments														
vel 1 - maximum	time at peak temperatur	e during sol	dering is 10-3	30 seconds										
or more informat	tion regarding material c	omposition p	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.4	mg	Supplier	Silicon (Si)	7440-21-3		0.4	mg
Die Attach Epoxy	0.1	mg		Epoxy resin	proprietary data		0.065	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.035	mg
Lead Frame	2.41		Supplier	Magnesium (Mg)	7439-95-4		0.0036	mg
			Supplier	Silicon (Si)	7440-21-3		0.0157	mg
			В	Nickel (Ni)	7440-02-0		0.0723	mg
			Supplier	Copper (Cu)	7440-50-8		2.3184	mg
Mold Compound-Black	2.98			Epoxy resin	proprietary data		0.1401	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.298	mg
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.3989	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1401	mg
Plating	0.07		Supplier	Palladium (Pd)	7440-05-3		0.0044	mg
			В	Nickel (Ni)	7440-02-0		0.0649	mg
			Supplier	Gold (Au)	7440-57-5		0.0007	mg
Wire Bond - Au	0.09	mg	Supplier	Gold (Au)	7440-57-5		0.09	mg